



Material Content Data Sheet



Sales Product Name		BAR 64-04W H6327		Issued		1. August 2018		
MA#		MA000856174						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		12	
	noble metal	gold	7440-57-5	0.007	0.12		1153	
	inorganic material	silicon	7440-21-3	0.059	0.98	1.10	9845	11010
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.89	44.07	438774	440625
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	762	762
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5237	
	plastics	epoxy resin	-	0.672	11.26		112590	
	inorganic material	silicondioxide	60676-86-0	2.421	40.58	52.36	405848	523675
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22249	22249
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1679	1679
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com